

ABSTRACT OF THE DISCLOSURE

A stacked semiconductor package, and a method of forming the same, including a plurality of stacked semiconductor devices on a substrate. The semiconductor devices are stacked in an active surface to backside configuration. The top semiconductor die is flipped over to face and the active surface of the semiconductor die directly below. An electrical connector can extend from a bond pad on the top semiconductor die to a redistribution circuit on the semiconductor die below. The redistribution circuit can be electrically connected to a substrate. Alternatively, an electrical connector extends from a bond pad on the top semiconductor die to a bond pad on a substrate.

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